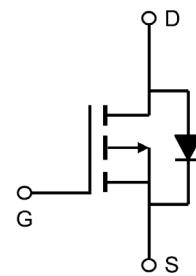
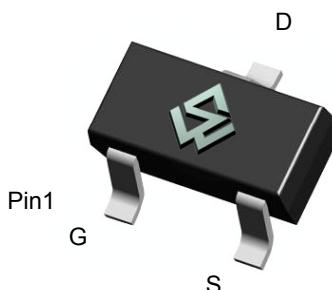


20V Single P-Channel Enhancement-Mode MOSFET

General Description	Product Summary		
• Low gate charge.	• BV_{DSS}	-20V	
• Use as a load switch.	• $R_{DS(on)}$ @ $V_{GS} = -4.5V$	< 145mΩ	
• Use in PWM applications	• $R_{DS(on)}$ @ $V_{GS} = -2.5V$	< 180mΩ	

SOT-23



Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 8	V
Drain Current ($T_A=25^\circ C$)	I_D	-2.5	A
Drain Current ($T_A=75^\circ C$)		-1.2	A
Pulsed Drain Current ^a	I_{DM}	-8	A
Power Dissipation ^b ($T_A=25^\circ C$)	P_D	1.25	W
Power Dissipation ^b ($T_A=75^\circ C$)		0.9	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 ~ +150	°C

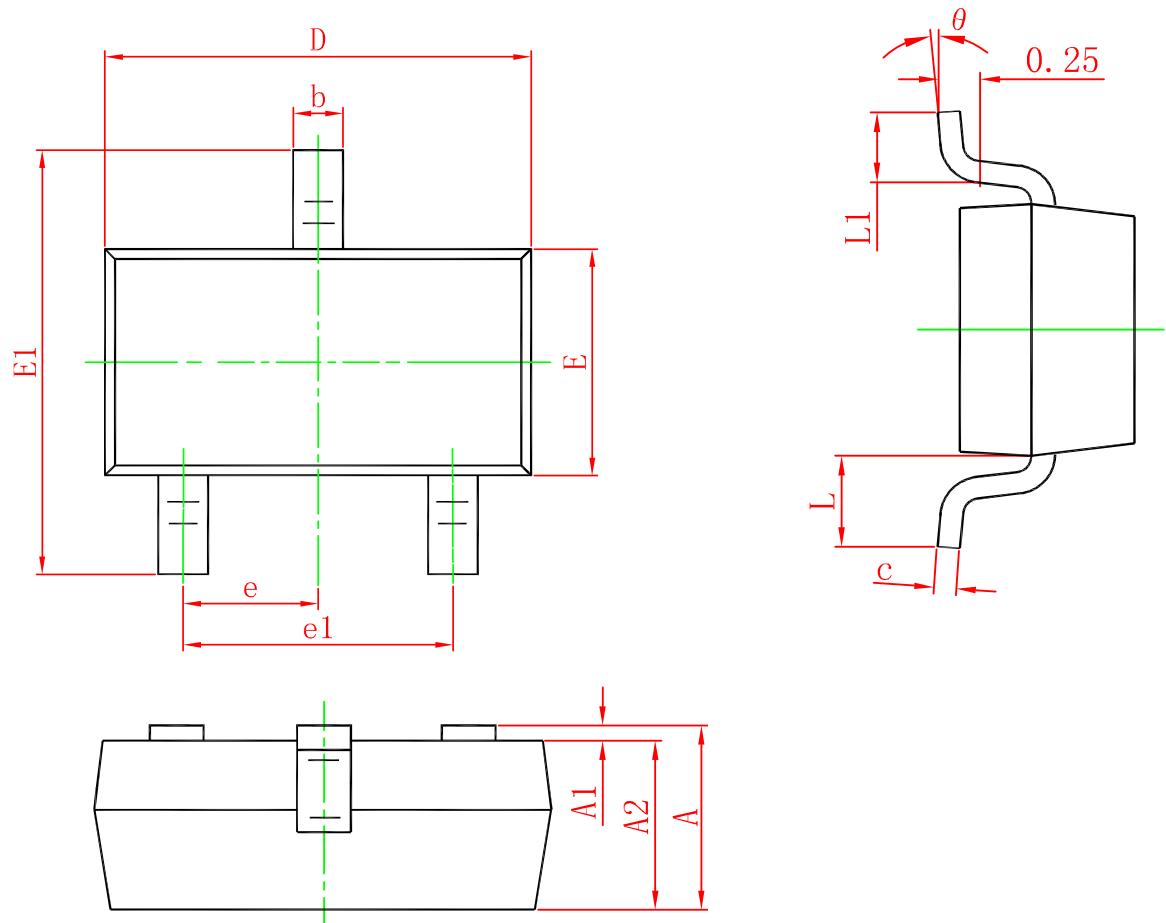
Thermal Characteristics

Parameter	Symbol	Maximum	Units
Junction-to-Ambient ^a ($t \leq 10s$)	$R_{\theta JA}$	100	°C/W
Junction-to-Ambient ^{a,d} (Steady-State)		130	°C/W
Junction-to-Lead (Steady-State)	$R_{\theta JL}$	90	°C/W

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)						
Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}$, $I_D = -250\mu\text{A}$	-20			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = -20\text{V}$, $V_{\text{GS}} = 0\text{V}$			-1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}} = \pm 8\text{V}$, $V_{\text{DS}} = 0\text{V}$			± 100	nA
On Characteristics						
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = -250\mu\text{A}$	-0.45		-0.9	V
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}} = -4.5\text{V}$, $I_D = -1.8\text{A}$			145	$\text{m}\Omega$
		$V_{\text{GS}} = -2.5\text{V}$, $I_D = -1.0\text{A}$			180	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{\text{DS}} = -4.5\text{V}$, $I_D = -2.5\text{A}$		15		S
Drain-Source Diode Characteristics						
V_{SD}	Diode Forward Voltage	$V_{\text{GS}} = 0\text{V}$, $I_S = -1.0\text{A}$			-1.3	V
I_S	Maximum Body-Diode Continuous Current				-1.6	A
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}} = -10\text{V}$, $V_{\text{GS}} = 0\text{V}$ $f = 1.0\text{MHz}$		680		pF
C_{oss}	Output Capacitance			320		pF
C_{rss}	Reverse Transfer Capacitance			100		pF
Switching Characteristics						
Q_g	Total Gate Charge	$V_{\text{DS}} = -10\text{V}$, $I_D = -2.5\text{A}$ $V_{\text{GS}} = -6\text{V}$		6.2		nC
Q_{gs}	Gate-Source Charge			1.5		nC
Q_{gd}	Gate-Drain Charge			2.3		nC
$t_{\text{D(ON)}}$	Turn-On Delay Time	$V_{\text{DD}} = -10\text{V}$, $I_D = -1\text{A}$ $V_{\text{GS}} = -4\text{V}$ $R_{\text{GEN}} = -6\text{ ohm}$		16		ns
t_r	Turn-On Rise Time			45		ns
$t_{\text{D(OFF)}}$	Turn-Off Delay Time			48		ns
t_f	Turn-Off Fall Time			39		ns

- a. Repetitive rating, Pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$
- b. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using $\leq 10\text{s}$ junction-to-ambient thermal resistance.
- c. The value of $R_{\theta_{JA}}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The value in any given application depends on the user's specific board design.
- d. The $R_{\theta_{JA}}$ is the sum of the thermal impedance from junction to lead $R_{\theta_{JL}}$ and lead to ambient.

SOT-23 Package Outline



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.	0.022 REF.		
θ	0.300	0.500	0.012	0.020

单击下面可查看定价，库存，交付和生命周期等信息

>>[SiliconWisdom\(矽睿半导体\)](#)